



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-12-11
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB13N80K5	TLD2*VJ85B52	A	3068	2018-12-11
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SIP	10.2-9.15-4.5	2	gull wing
Comment	D2PAK		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.17	Die - Leadframe	123
Lead	12.14	Soft solder	8799

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	12.14	Soft solder	8799
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	12.14	Soft solder	955010

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TLD2*VJ85852					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	13.989	mg	supplier	die	Silicon (Si)	7440-21-3		13.673	mg	977411	9908
				supplier	metallization	Aluminium (Al)	7429-90-5		0.127	mg	9079	92
				supplier	Passivation	Silicon Oxide	7631-86-9		0.056	mg	4003	41
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	500	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.093	mg	6648	67
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.033	mg	2359	24
Leadframe	M-004 Copper and its alloys	778.633	mg	supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	998592	563433
				supplier	alloy	Iron (Fe)	7439-89-6		0.779	mg	1000	564
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.234	mg	301	170
				supplier	metallization	Nickel (Ni)	7440-02-0		0.077	mg	99	56
				supplier	metallization	Phosphorus (P)	7723-14-0		0.006	mg	8	4
Soft solder	Solder	12.714	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	12.142	mg	955010	8799
				supplier	solder	Silver (Ag)	7440-22-4		0.318	mg	25012	230
				supplier	solder	Tin (Sn)	7440-31-5		0.254	mg	19978	184
Bonding wires	M-011 Other inorganic materials	0.774	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.771	mg	996124	559
				supplier	wire	Magnesium (Mg)	7439-95-4		0.003	mg	3876	2
Encapsulation	M-011 Other inorganic materials	571.401	mg	supplier	mold compound	Silica, vitreous	60676-86-0		499.976	mg	875000	362301
				supplier	mold compound	Tetramethyl-biphenyl-diy-bis oxymethylene-b	85954-11-6		22.856	mg	40000	16562
				supplier	mold compound	Epoxy Resin	25068-38-6		17.142	mg	30000	12422
				supplier	mold compound	phenol resin	29690-82-2		28.570	mg	50000	20703
				supplier	mold compound	Carbon black	1333-86-4		2.857	mg	5000	2070
Connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804